

# Layer123 Prototype Schedule Update

RIKEN/RBRC

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# Layer 1,2,3 Prototype

- May 12<sup>th</sup> ~ June 9<sup>th</sup> : HDI component mounting (REPIC)
- June 12<sup>th</sup> ~ June 16<sup>th</sup> : Shipping from RIKEN to BNL
- June 16<sup>th</sup> ~ June 30<sup>th</sup> : Silicon module assembly
- July 1<sup>st</sup> ~ : prototype test @ test bench
- To be arranged travel of two students (Hidekazu Masuda and Ryota Kawashima) for testing.

# Status

- Silicon Sensors: Delivered by the end of March. In preparation for exporting.
- Bad silicon sensors : 2 ~ 3 samples are available for both type A&B. To be delivered last week of May.
- Bad HDI samples : To be delivered after investigation the cause of failure.
- No component mounted HDIs. To be shipped to BNL immediately.
- Graphite sheet : waiting for Kaneka company's quote.